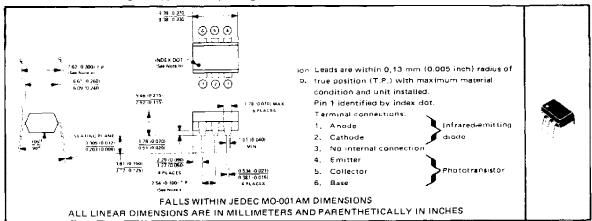
COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Phototransistor
- High Direct-Current Transfer Ratio
- High-Voltage Electrical Isolation . . . 5000-V Rating
- Plastic Dual-In-Line Package
- High-Speed Switching: $t_r = 2 \mu s$, $t_f = 2 \mu s$ Typical
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays, and Pulse Transformers

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an n-p-n silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.



absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output Voltage
Collector-Base Voltage
Collector-Emitter Voltage (See Note 1)
Emitter-Collector Voltage
Emitter-Base Voltage
Input-Diode Reverse Voltage
Input-Diode Continuous Forward Current
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature:
Infrared-Emitting Diode (See Note 2)
Phototransistor (See Note 3)
Total, Infrared-Emitting Diode plus Phototransistor (See Note 4)
Storage Temperature Range
Lead Temperature 1,6 mm (1/16 inch) from Case for 10 Seconds

NOTES 1. This value applies when the base emitter diode is open-circuited

- 2. Denote linearly to 100°C free air temperature at the rate of 2 mW/°C.
- 3. Denate linearly to $100^{\circ}C$ free-air temperature at the rate of 2 mW/ C.
- Defaite linearly to 100°C free-air temperature at the rate of 3.33 mW/°C.

Texas Instruments

TIL124, TIL125, TIL126 OPTOCOUPLERS

electrical characteristics at 25°C free-air temperature

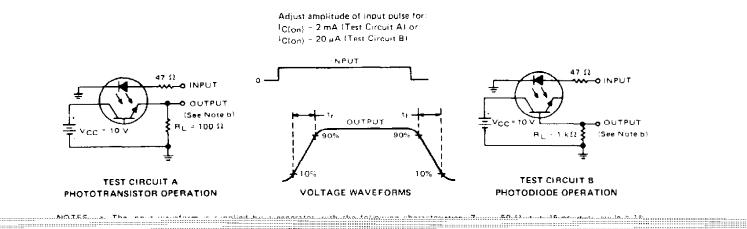
PARAMETER			TEST CONDITIONS	TIL124		TIL 125			TIL 126				
PARAMETER		MIN		TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
V(8R)C80	Collector-Base Breakdown Voltage		l _C = 10 μA, l _E = 0, l _E = 0	70			70		-	70			٧
VIBR)CEO	Collector-Emitter Breakdown Voltage		I _C = 1 mA, I _B = 0,	30			30	·		30			٧
VIBR)EBO	Emitter-Base Breakdown Voltage		IE = 10 µA, IC = 0, IF = 0	7			7			7			٧
IR	Input Diode Static Reverse Current		V _R = 3 V			10			10			10	ДА
[†] C(an)	On-State Collector Current	Phototransistor Operation	VCE = 10 V, Ir = 10 mA.	1	3		2	5		5	9		mA
		Photodiode Operation	V _{CB} = 10 V, I _F = 10 mA, I _E = 0	5	20		5	20		5	20		Ац
^I C(off)	Off-State Collector Current	Oneration	V _{CE} = 10 V, I _F + 0 I _B = 0		1	50		1	50		1	50	nA
		Photodiode Operation	V _{CB} = 10 V, I _F = 0, I _E = 0		0.1	20		0.1	20		0.1	20	1
μŁΕ	Transistor Static Forward Current Transfer Ratio		VCE = 5 V, IC = 10 mA, ip = 0	50	100		100	200		100	550		
V _F	Input Diode Static Forward Voltage		IF - 10 mA		1.2	1,4		1.2	1,4		1.2	1.4	v
VCE(sat)	Collector-Emitter Saturation Voltage		1 _C = 1 mA, I _F = 10 mA, I _B = 0		0.25	0.4		0.25	0.4		0.25	0.4	V
r _{io}	Input-to-Output Internal Resistance		V _{in-out} = 500 V, See Note 5	10''			10''			10 ¹			Ω
C _{ia}	Input-to-Output Capacitance		V _{in-out} = 0, f = 1 MHz, See Note 5		1	1.3		1	1.3		1	1.3	pF

NOTE 5: These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together.

switching characteristics at 25°C free-air temperature

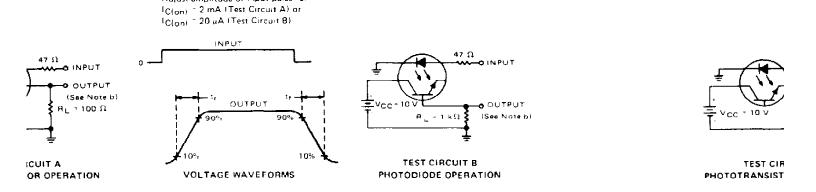
	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t,	Rise Time	Phototransistor	V _{CC} = 10 V, I _{C(on)} = 2 mA,R _L = 100 Ω,		5	10	
T _f	Fall Time	Operation	See Test Circuit A of Figure 1		5	10	μş
t _r	Rise Time	Photodiode	$V_{CC} = 10 \text{ V}, I_{C(on)} = 20 \mu\text{A,RL} = 1 \text{k}\Omega.$		1		
tf	Fall Time	Operation	See Test Circuit B of Figure 1		1		цs

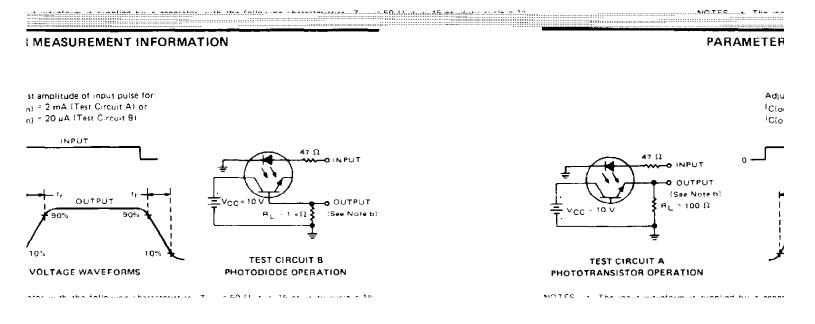
PARAMETER MEASUREMENT INFORMATION



PARAMETER MEASUREMENT INFORMATION

Adjust amplitude of input pulse for

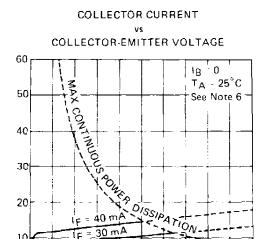




C-Collector Current- mA

10

TYPICAL CHARACTERISTICS



TIL124

V_{CE}-Collector-Emitter Voltage-V FIGURE 3

10 12 14

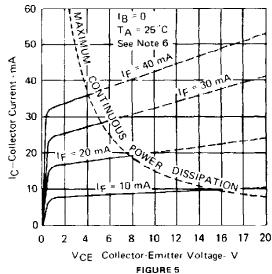
18 20

= <u>20</u> mA

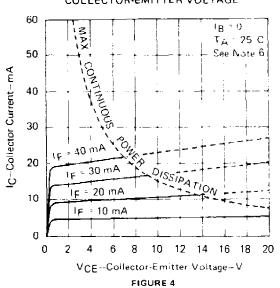
8

IF = 10 mA



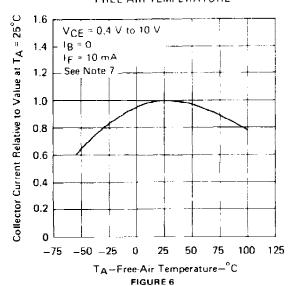


TIL125 **COLLECTOR CURRENT** COLLECTOR-EMITTER VOLTAGE



RELATIVE ON-STATE COLLECTOR CURRENT

FREE-AIR TEMPERATURE

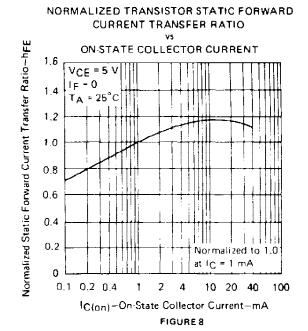


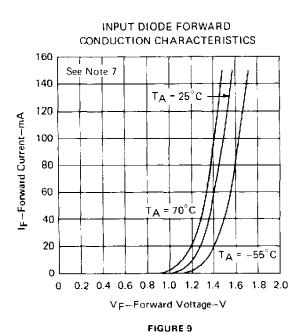
NOTES 6. Pulse operation of input diode is required for operation beyond limits shown by dotted lines.

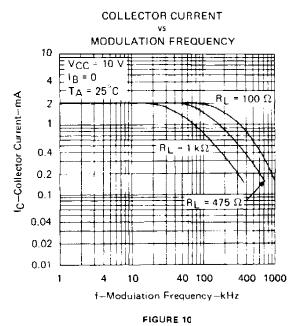
7. These parameters were measured using pulse techniques, two - 1 ms, duty cycle 6, 2%

TYPICAL CHARACTERISTICS

OFF-STATE COLLECTOR CURRENT FREE-AIR TEMPERATURE 10 000 V_{CE} = 10 V 4 000 Ψ 1B = 0 IF = 0 1 000 IC(off)- Off State Collector Current 400 100 40 10 4 0.4 0.1 10 0 60 70 50 TA-Free-Air Temperature-2C FIGURE 7







NOTE 7: These parameters were measured using pulse techniques, $t_{\rm vv}$ = 1 ms, duty cycle $\lesssim 2\%$.



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